

# DATA SHEET

**74LVC322244A; 74LVCH322244A**  
32-bit buffer/line driver; with 30  $\Omega$   
series termination resistors; 5 V  
input/output tolerant; 3-state

Product specification  
File under Integrated Circuits, IC24

1999 Aug 31

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## 74LVC322244A; 74LVCH322244A

### FEATURES

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range of 1.2 to 3.6 V
- CMOS low power consumption
- MULTIBYTE™ flow-through standard pin-out architecture
- Low inductance multiple power and ground pins for minimum noise and ground bounce
- Direct interface with TTL levels
- Bus hold on data inputs (74LVCH322244A only)
- Integrated 30  $\Omega$  termination resistors
- Typical output ground bounce voltage:  
 $V_{OLP} < 0.8$  V at  $V_{CC} = 3.3$  V;  $T_{amb} = 25$  °C
- Typical output  $V_{OH}$  undershoot voltage:  
 $V_{OHV} > 2$  V at  $V_{CC} = 3.3$  V;  $T_{amb} = 25$  °C
- Power-off disabled outputs, permitting live insertion
- Plastic fine-pitch ball grid array package.

### DESCRIPTION

The 74LVC(H)322244A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families. Inputs can be driven from either 3.3 or 5 V devices. In 3-state operation, outputs can handle 5 V. These features allow the use of these devices in a mixed 3.3 and 5 V environment.

The 74LVC(H)322244A is a 32-bit non-inverting buffer/line driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs  $1\overline{OE}$  and  $2\overline{OE}$ . A HIGH on input  $n\overline{OE}$  causes the outputs to assume a high-impedance OFF-state.

The 74LVC(H)322244A is designed with 30  $\Omega$  series termination resistors in both HIGH and LOW output stages to reduce line noise.

To ensure the high-impedance state during power-up or power-down, input  $n\overline{OE}$  should be tied to  $V_{CC}$  through a pull-up resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The 74LVCH322244A bus hold data input circuit eliminates the need for external pull-up resistors to hold unused or floating data inputs at a valid logic level (see Fig.3).

### QUICK REFERENCE DATA

Ground = 0 V;  $T_{amb} = 25$  °C;  $t_r = t_f \leq 2.5$  ns.

| SYMBOL            | PARAMETER  | CONDITIONS                       | TYPICAL | UNIT |
|-------------------|--|----------------------------------|---------|------|
| $t_{PHL}/t_{PLH}$ | propagation delay nA <sub>n</sub> to nY <sub>n</sub> | $C_L = 50$ pF; $V_{CC} = 3.3$ V  | 2.9     | ns   |
| $C_I$             | input capacitance                                    |                                  | 5.0     | pF   |
| $C_{PD}$          | power dissipation capacitance per buffer             | $V_I = GND$ to $V_{CC}$ ; note 1 | 25      | pF   |

### Note

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

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### FUNCTION TABLE

See note 1.

| INPUT                   |               | OUTPUT        |
|-------------------------|---------------|---------------|
| $\overline{\text{nOE}}$ | $\text{nA}_n$ | $\text{nY}_n$ |
| L                       | L             | L             |
| L                       | H             | H             |
| H                       | X             | Z             |

### Note

- H = HIGH voltage level;  
L = LOW voltage level;  
X = don't care;  
Z = high-impedance OFF-state.

### ORDERING INFORMATION

| TYPE NUMBER     | PACKAGES          |      |         |          |          |
|-----------------|-------------------|------|---------|----------|----------|
|                 | TEMPERATURE RANGE | PINS | PACKAGE | MATERIAL | CODE     |
| 74LVC322244AEC  | -40 to +85 °C     | 96   | LFBGA96 | plastic  | SOT536-1 |
| 74LVCH322244AEC |                   | 96   | LFBGA96 | plastic  | SOT536-1 |

### PINNING

| SYMBOL                  | DESCRIPTION                               |
|-------------------------|---|
| $\text{nA}_n$           | data inputs                               |
| $\text{nY}_n$           | data outputs                              |
| GND                     | ground (0 V)                              |
| $\overline{\text{nOE}}$ | 3-state output enable inputs (active LOW) |
| $V_{CC}$                | DC supply voltage                         |

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|   |                   |                 |                 |                 |                 |                 |                 |                   |                   |                 |                 |                 |                 |                 |                 |                   |
|---|-------------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-------------------|-------------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-------------------|
| 6 | 1A <sub>1</sub>   | 1A <sub>3</sub> | 2A <sub>1</sub> | 2A <sub>3</sub> | 3A <sub>1</sub> | 3A <sub>3</sub> | 4A <sub>1</sub> | 4A <sub>2</sub>   | 5A <sub>1</sub>   | 5A <sub>3</sub> | 6A <sub>1</sub> | 6A <sub>3</sub> | 7A <sub>1</sub> | 7A <sub>3</sub> | 8A <sub>1</sub> | 8A <sub>2</sub>   |
| 5 | 1A <sub>0</sub>   | 1A <sub>2</sub> | 2A <sub>0</sub> | 2A <sub>2</sub> | 3A <sub>0</sub> | 3A <sub>2</sub> | 4A <sub>0</sub> | 4A <sub>3</sub>   | 5A <sub>0</sub>   | 5A <sub>2</sub> | 6A <sub>0</sub> | 6A <sub>2</sub> | 7A <sub>0</sub> | 7A <sub>2</sub> | 8A <sub>0</sub> | 8A <sub>3</sub>   |
| 4 | 2 $\overline{O}E$ | GND             | V <sub>CC</sub> | GND             | GND             | V <sub>CC</sub> | GND             | 3 $\overline{O}E$ | 6 $\overline{O}E$ | GND             | V <sub>CC</sub> | GND             | GND             | V <sub>CC</sub> | GND             | 7 $\overline{O}E$ |
| 3 | 1 $\overline{O}E$ | GND             | V <sub>CC</sub> | GND             | GND             | V <sub>CC</sub> | GND             | 4 $\overline{O}E$ | 5 $\overline{O}E$ | GND             | V <sub>CC</sub> | GND             | GND             | V <sub>CC</sub> | GND             | 8 $\overline{O}E$ |
| 2 | 1Y <sub>0</sub>   | 1Y <sub>2</sub> | 2Y <sub>0</sub> | 2Y <sub>2</sub> | 3Y <sub>0</sub> | 3Y <sub>2</sub> | 4Y <sub>0</sub> | 4Y <sub>3</sub>   | 5Y <sub>0</sub>   | 5Y <sub>2</sub> | 6Y <sub>0</sub> | 6Y <sub>2</sub> | 7Y <sub>0</sub> | 7Y <sub>2</sub> | 8Y <sub>0</sub> | 8Y <sub>3</sub>   |
| 1 | 1Y <sub>1</sub>   | 1Y <sub>3</sub> | 2Y <sub>1</sub> | 2Y <sub>3</sub> | 3Y <sub>1</sub> | 3Y <sub>3</sub> | 4Y <sub>1</sub> | 4Y <sub>2</sub>   | 5Y <sub>1</sub>   | 5Y <sub>3</sub> | 6Y <sub>1</sub> | 6Y <sub>3</sub> | 7Y <sub>1</sub> | 7Y <sub>3</sub> | 8Y <sub>1</sub> | 8Y <sub>2</sub>   |
|   | A                 | B               | C               | D               | E               | F               | G               | H                 | J                 | K               | L               | M               | N               | P               | R               | T                 |

Fig.1 Pin configuration.

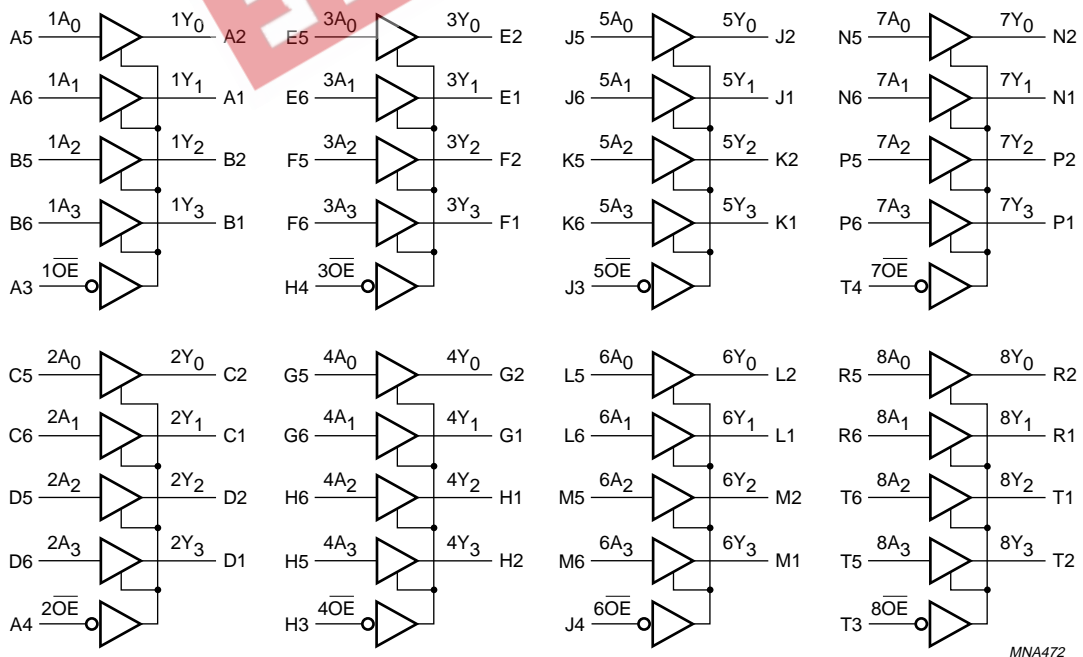


Fig.2 Logic symbol.

32-bit buffer/line driver; with 30 Ω series termination resistors; 5 V input/output tolerant; 3-state

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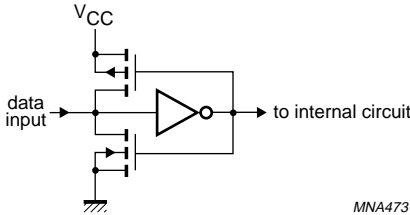


Fig.3 Bus hold circuit.

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#### RECOMMENDED OPERATING CONDITIONS

| SYMBOL  | PARAMETER                       | CONDITIONS                               | LIMITS |                 | UNIT |
|---|---------------------------------|--|--------|-----------------|------|
|   |                                 |  | MIN.   | MAX.            |      |
| V <sub>CC</sub>   | DC supply voltage               | for max. speed performance               | 2.7    | 3.6             | V    |
|   |                                 | for low-voltage applications             | 1.2    | 3.6             | V    |
| V <sub>I</sub>  | DC input voltage                |  | 0      | 5.5             | V    |
| V <sub>O</sub>  | DC output voltage               | output HIGH or LOW state                 | 0      | V <sub>CC</sub> | V    |
|   |                                 | 3-state                                  | 0      | 5.5             | V    |
| T <sub>amb</sub>  | operating ambient temperature   | see DC and AC characteristics per device | -40    | +85             | °C   |
| t <sub>r</sub> , t <sub>f</sub> ( $\Delta t/\Delta f$ ) | input rise and fall times ratio | V <sub>CC</sub> = 1.2 to 2.7 V           | 0      | 20              | ns/V |
|   |                                 | V <sub>CC</sub> = 2.7 to 3.6 V           | 0      | 10              |      |

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134); voltages are referenced to GND (ground = 0 V).

| SYMBOL                             | PARAMETER                         | CONDITIONS   | MIN. | MAX.                  | UNIT |
|------------------------------------|-----------------------------------|--|------|-----------------------|------|
| V <sub>CC</sub>                    | DC supply voltage                 |  | -0.5 | +6.5                  | V    |
| V <sub>I</sub>                     | DC input voltage                  | note 1   | -0.5 | +6.5                  | V    |
| I <sub>IK</sub>                    | DC input diode current            | V <sub>I</sub> < 0   | -    | -50                   | mA   |
| I <sub>OK</sub>                    | DC output diode current           | V <sub>O</sub> > V <sub>CC</sub> or V <sub>O</sub> < 0; note 1 | -    | ±50                   | mA   |
| V <sub>O</sub>                     | DC output voltage                 | output HIGH or LOW state; note 1                               | -0.5 | V <sub>CC</sub> + 0.5 | V    |
|                                    |                                   | output 3-state; note 1   | -0.5 | +6.5                  | V    |
| I <sub>O</sub>                     | DC output source or sink current  | V <sub>O</sub> = 0 to V <sub>CC</sub>                          | -    | ±50                   | mA   |
| I <sub>CC</sub> , I <sub>GND</sub> | DC V <sub>CC</sub> or GND current |  | -    | ±100                  | mA   |
| T <sub>stg</sub>                   | storage temperature               |  | -65  | +150                  | °C   |
| P <sub>D</sub>                     | power dissipation per packages    | temperature range: -40 to +85 °C; note 2                       | -    | 1000                  | mW   |

#### Notes

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- Above 70 °C the value of P<sub>D</sub> derates linearly with 1.8 mW/K.

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**DC CHARACTERISTICS**

Over recommended operating conditions; voltage are referenced to GND (ground = 0 V).

| SYMBOL            | PARAMETER                           | TEST CONDITIONS  |                     | T <sub>amb</sub> (°C) |                     |      | UNIT |
|-------------------|-------------------------------------|--|---------------------|-----------------------|---------------------|------|------|
|                   |                                     | OTHER  | V <sub>CC</sub> (V) | -40 to +85            |                     |      |      |
|                   |                                     |  |                     | MIN.                  | TYP. <sup>(1)</sup> | MAX. |      |
| V <sub>IH</sub>   | HIGH-level input voltage            |  | 1.2                 | V <sub>CC</sub>       | -                   | -    | V    |
|                   |                                     |  | 2.7 to 3.6          | 2.0                   | -                   | -    |      |
| V <sub>IL</sub>   | LOW-level input voltage             |  | 1.2                 | -                     | -                   | GND  | V    |
|                   |                                     |  | 2.7 to 3.6          | -                     | -                   | 0.8  |      |
| V <sub>OH</sub>   | HIGH-level output voltage           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>I <sub>O</sub> = -6 mA<br>I <sub>O</sub> = -100 μA<br>I <sub>O</sub> = -12 mA | 2.7                 | V <sub>CC</sub> - 0.5 | -                   | -    | V    |
|                   |                                     |  | 3.0                 | V <sub>CC</sub> - 0.2 | V <sub>CC</sub>     | -    |      |
|                   |                                     |  | 3.0                 | V <sub>CC</sub> - 0.8 | -                   | -    |      |
| V <sub>OL</sub>   | LOW-level output voltage            | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub><br>I <sub>O</sub> = 6 mA<br>I <sub>O</sub> = 100 μA<br>I <sub>O</sub> = 12 mA    | 2.7                 | -                     | -                   | 0.40 | V    |
|                   |                                     |  | 3.0                 | -                     | -                   | 0.20 |      |
|                   |                                     |  | 3.0                 | -                     | -                   | 0.55 |      |
| I <sub>I</sub>    | input leakage current               | V <sub>I</sub> = 5.5 V or GND;<br>note 2   | 3.6                 | -                     | ±0.1                | ±5   | μA   |
| I <sub>oz</sub>   | 3-state output OFF-state current    | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ;<br>V <sub>O</sub> = 5.5 V or GND   | 3.6                 | -                     | 0.1                 | ±5   | μA   |
| I <sub>off</sub>  | power-off leakage supply current    | V <sub>I</sub> or V <sub>O</sub> = 5.5 V   | 0.0                 | -                     | 0.1                 | ±10  | μA   |
| I <sub>CC</sub>   | quiescent supply current            | V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0  | 3.6                 | -                     | 0.1                 | 40   | μA   |
| ΔI <sub>CC</sub>  | additional quiescent supply current | V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0;<br>per control pin   | 2.7 to 3.6          | -                     | 5                   | 500  | μA   |
|                   |                                     | V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0;<br>per data input pin  | 2.7 to 3.6          | -                     | 5                   | 500  | μA   |
| I <sub>BHL</sub>  | bus hold LOW sustaining current     | V <sub>I</sub> = 0.8 V;<br>notes 3, 4 and 5  | 3.0                 | 75                    | -                   | -    | μA   |
| I <sub>BHH</sub>  | bus hold HIGH sustaining current    | V <sub>I</sub> = 2.0 V;<br>notes 3, 4 and 5  | 3.0                 | -75                   | -                   | -    | μA   |
| I <sub>BHLO</sub> | bus hold LOW overdrive current      | notes 3, 4 and 6   | 3.6                 | 450                   | -                   | -    | μA   |
| I <sub>BHHO</sub> | bus hold HIGH overdrive current     | notes 3, 4 and 6   | 3.6                 | -450                  | -                   | -    | μA   |

**Notes**

1. All typical values are at V<sub>CC</sub> = 3.3 V and T<sub>amb</sub> = 25 °C.
2. For bus hold parts the bus hold circuit is switched off when V<sub>I</sub> exceeds V<sub>CC</sub> allowing 5.5 V on the input terminal.
3. Valid for data inputs of bus hold parts only (LVCH32xxx-A).
4. For data inputs only. Control inputs do not have a bus hold circuit.
5. The specified sustaining current at the data input holds the input below the specified V<sub>I</sub> level.
6. The specified overdrive current at the data input forces the data input to the opposite logic input level.

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**AC CHARACTERISTICS**

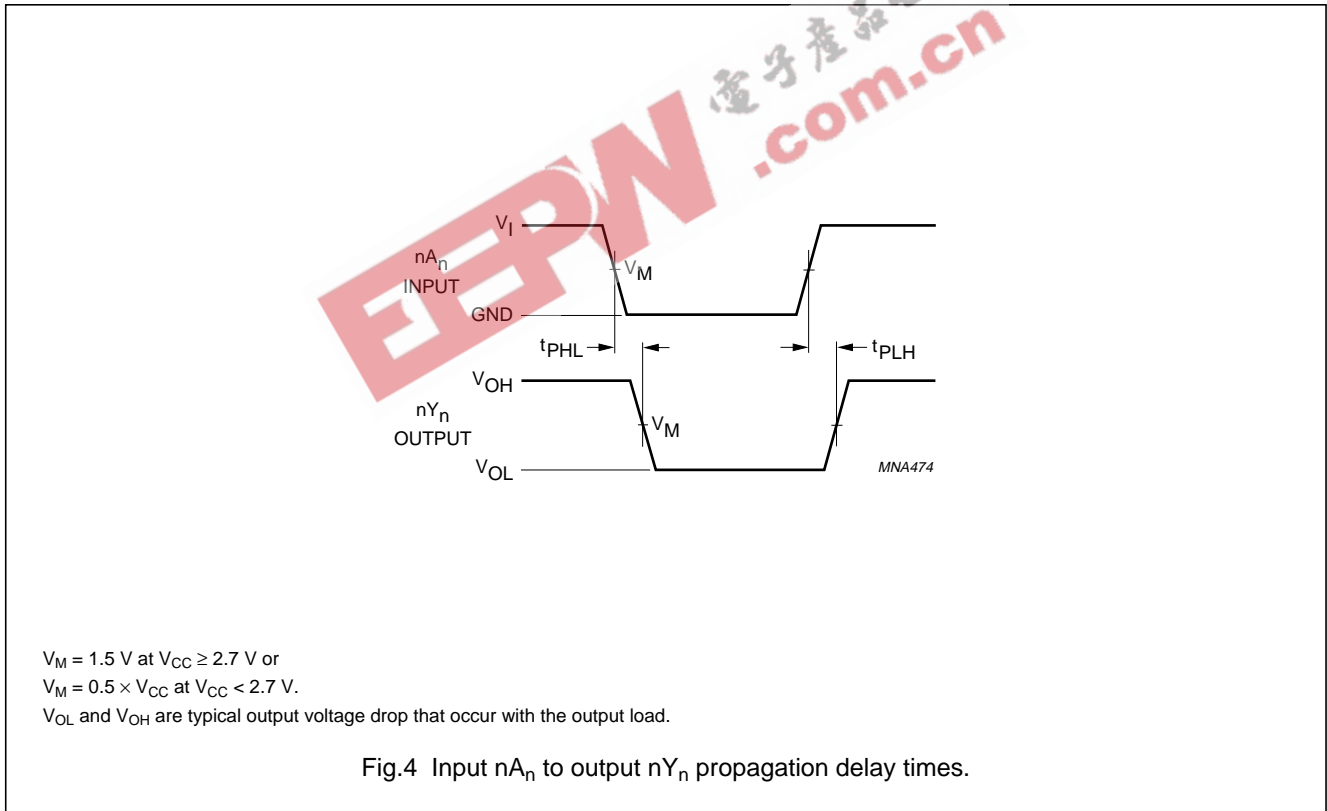
Ground = 0 V;  $t_r = t_f \leq 2.5$  ns;  $C_L = 50$  pF;  $R_L = 500$  Ω.

| SYMBOL            | PARAMETER   | TEST CONDITIONS  |              | $T_{amb} = -40$ to $+85$ °C |                     |      | UNIT |
|-------------------|---|------------------|--------------|-----------------------------|---------------------|------|------|
|                   |   | WAVEFORMS        | $V_{CC}$ (V) | MIN.                        | TYP. <sup>(1)</sup> | MAX. |      |
| $t_{PHL}/t_{PLH}$ | propagation delay<br>$nA_n$ to $nY_n$                     | see Figs 4 and 6 | 2.7          | 1.5                         | –                   | 7.3  | ns   |
|                   |   |                  | 3.0 to 3.6   | 1.5                         | 2.9                 | 6.3  |      |
| $t_{PZH}/t_{PZL}$ | 3-state output enable time<br>$n\overline{OE}$ to $nY_n$  | see Figs 5 and 6 | 2.7          | 1.5                         | –                   | 8.1  | ns   |
|                   |   |                  | 3.0 to 3.6   | 1.5                         | 3.4                 | 7.1  |      |
| $t_{PHZ}/t_{PLZ}$ | 3-state output disable time<br>$n\overline{OE}$ to $nY_n$ | see Figs 5 and 6 | 2.7          | 1.5                         | –                   | 6.0  | ns   |
|                   |   |                  | 3.0 to 3.6   | 1.5                         | 2.8                 | 5.0  |      |

**Note**

1. All typical values are measured at  $V_{CC} = 3.3$  V and  $T_{amb} = 25$  °C.

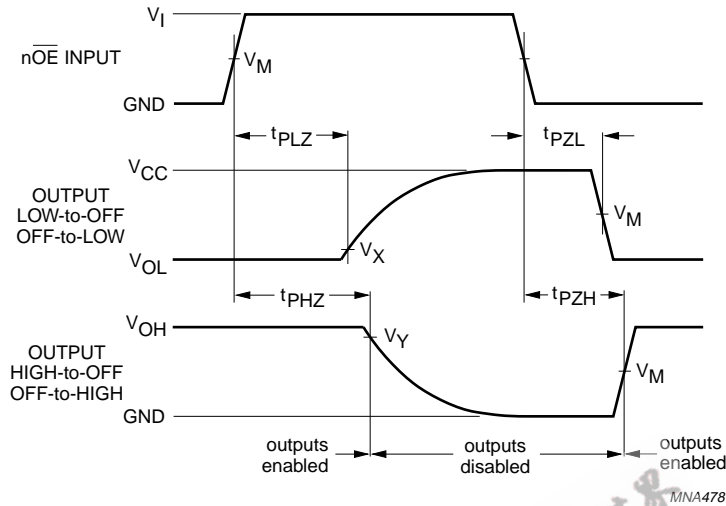
**AC WAVEFORMS**





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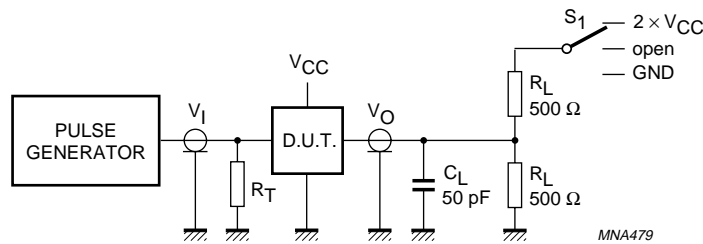
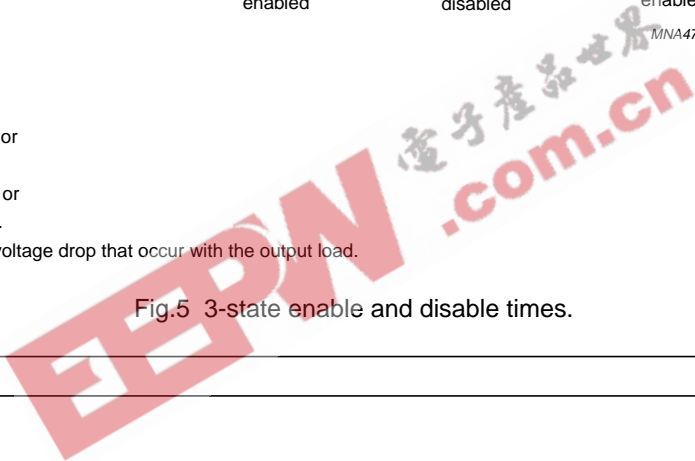
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$V_M = 1.5\text{ V}$  at  $V_{CC} \geq 2.7\text{ V}$  or  
 $V_M = 0.5 \times V_{CC}$  at  $V_{CC} < 2.7\text{ V}$ ;  
 $V_X = V_{OL} + 0.3\text{ V}$  at  $V_{CC} \geq 2.7\text{ V}$  or  
 $V_X = V_{OL} + 0.1\text{ V}$  at  $V_{CC} < 2.7\text{ V}$ ;  
 $V_Y = V_{OH} - 0.3\text{ V}$  at  $V_{CC} \geq 2.7\text{ V}$  or  
 $V_Y = V_{OH} - 0.1\text{ V}$  at  $V_{CC} < 2.7\text{ V}$ .

$V_{OL}$  and  $V_{OH}$  are typical output voltage drop that occur with the output load.

Fig.5 3-state enable and disable times.



| TEST                               | S <sub>1</sub>      |
|------------------------------------|---------------------|
| t <sub>PLH</sub> /t <sub>PHL</sub> | open                |
| t <sub>PLZ</sub> /t <sub>PZL</sub> | 2 × V <sub>CC</sub> |
| t <sub>PHZ</sub> /t <sub>PZH</sub> | GND                 |

| V <sub>CC</sub> | V <sub>I</sub>  |
|-----------------|-----------------|
| < 2.7 V         | V <sub>CC</sub> |
| 2.7 to 3.6 V    | 2.7 V           |

Definitions for test circuit:  
 $R_L$  = load resistor.  
 $C_L$  = load capacitance including jig and probe capacitance.  
 $R_T$  = termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

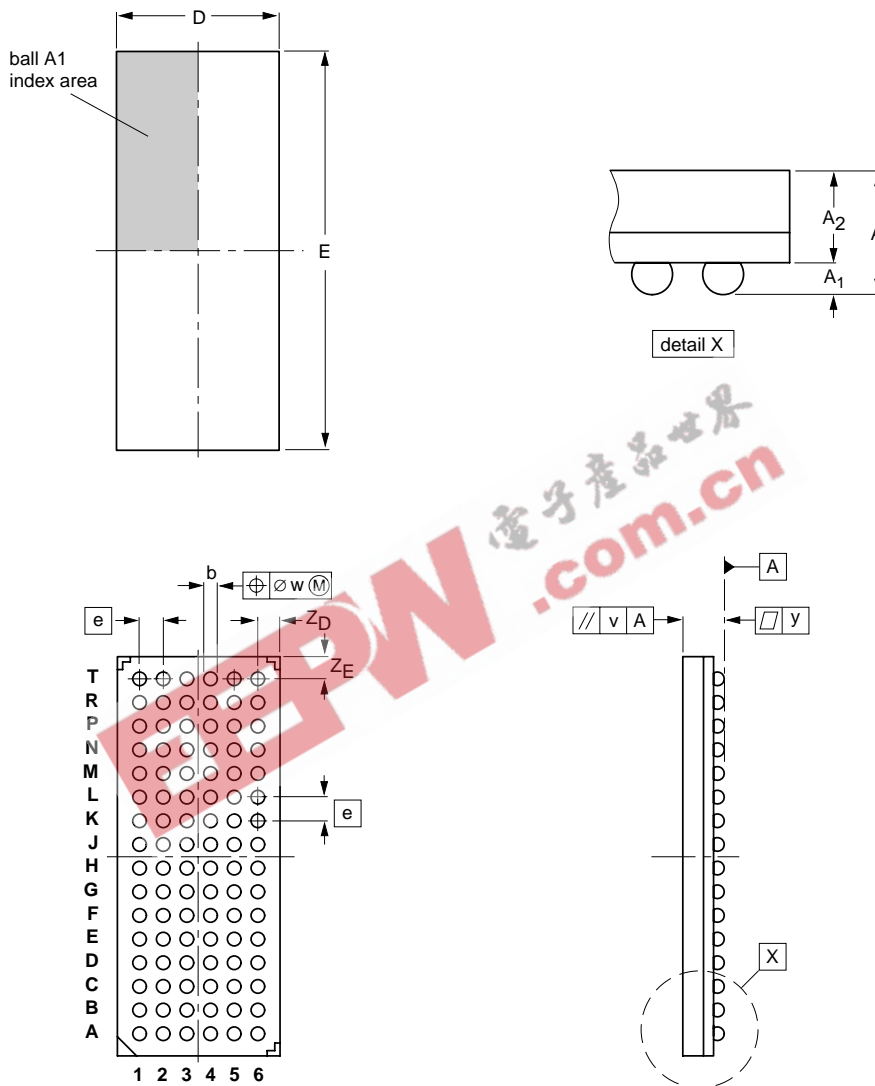
Fig.6 Load circuitry for switching times.

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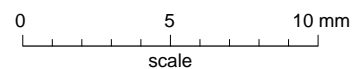
PACKAGE OUTLINE

LFBGA96: plastic low profile fine-pitch ball grid array package; 96 balls; body 13.5 x 5.5 x 1.05 mm SOT536-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A <sub>1</sub> | A <sub>2</sub> | b            | D          | E            | e   | v   | w    | y   | Z <sub>D</sub> | Z <sub>E</sub> |
|------|--------|----------------|----------------|--------------|------------|--------------|-----|-----|------|-----|----------------|----------------|
| mm   | 1.5    | 0.41<br>0.31   | 1.2<br>0.9     | 0.51<br>0.41 | 5.6<br>5.4 | 13.6<br>13.4 | 0.8 | 0.2 | 0.15 | 0.1 | 0.93<br>0.58   | 0.93<br>0.58   |



| OUTLINE VERSION | REFERENCES |       |      |  | EUROPEAN PROJECTION | ISSUE DATE           |
|-----------------|------------|-------|------|--|---------------------|----------------------|
|                 | IEC        | JEDEC | EIAJ |  |                     |                      |
| SOT536-1        |            |       |      |  |                     | 98-11-25<br>99-06-03 |

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## SOLDERING

### Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

### Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

### Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

### Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

32-bit buffer/line driver; with 30  $\Omega$  series termination resistors; 5 V input/output tolerant; 3-state

74LVC322244A;  
74LVCH322244A

#### Suitability of surface mount IC packages for wave and reflow soldering methods

| PACKAGE                                | SOLDERING METHOD                  |                       |
|--|-----------------------------------|-----------------------|
|  | WAVE                              | REFLOW <sup>(1)</sup> |
| BGA, LFBGA, SQFP, TFBGA                | not suitable                      | suitable              |
| HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS | not suitable <sup>(2)</sup>       | suitable              |
| PLCC <sup>(3)</sup> , SO, SOJ          | suitable                          | suitable              |
| LQFP, QFP, TQFP                        | not recommended <sup>(3)(4)</sup> | suitable              |
| SSOP, TSSOP, VSO                       | not recommended <sup>(5)</sup>    | suitable              |

#### Notes

- All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the "Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods".
- These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
- If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

#### DEFINITIONS

| Data sheet status   |   |
|---|---|
| Objective specification   | This data sheet contains target or goal specifications for product development.       |
| Preliminary specification   | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification   | This data sheet contains final product specifications.                                |
| Limiting values   |   |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. |   |
| Application information   |   |
| Where application information is given, it is advisory and does not form part of the specification.   |   |

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